



**NIST Interagency Report  
NIST IR 8532 ipd**

**Workshop on Enhancing Security of  
Devices and Components Across the  
Supply Chain**

Initial Public Draft

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1 **Abstract**

2 NIST hosted an in-person, all-day workshop on February 27, 2024, to discuss existing and  
3 emerging cybersecurity threats and mitigation techniques for semiconductors throughout their  
4 life cycle. The workshop obtained valuable feedback from industry, academia, and government  
5 to inform NIST’s development of cybersecurity and supply chain standards, guidance, and  
6 recommended practices. The discussion focused on semiconductor development and  
7 highlighted cybersecurity measurements and metrics that utilize reference data sets to  
8 facilitate the testing, attestation, certification, verification, and validation of semiconductor  
9 components. It also emphasized the use of automated cybersecurity tools and techniques to  
10 secure manufacturing environments throughout the development life cycle. This report  
11 summarizes the content that was presented and discussed at the workshop.

12 **Keywords**

13 cybersecurity; hardware security; measurement; semiconductors; supply chain; vulnerabilities.

14 **Reports on Computer Systems Technology**

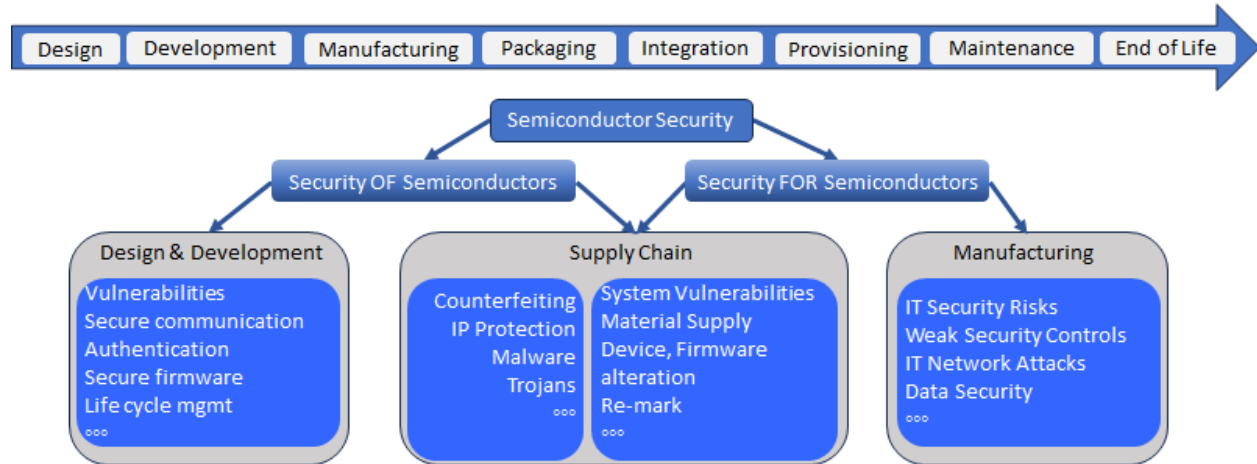
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16 Technology (NIST) promotes the U.S. economy and public welfare by providing technical  
17 leadership for the Nation’s measurement and standards infrastructure. ITL develops tests, test  
18 methods, reference data, proof of concept implementations, and technical analyses to advance  
19 the development and productive use of information technology. ITL’s responsibilities include  
20 the development of management, administrative, technical, and physical standards and  
21 guidelines for the cost-effective security and privacy of other than national security-related  
22 information in federal information systems.

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48 **1. Introduction**

49 Semiconductor-based hardware is the foundation of modern-day electronics — from  
50 smartphones, computers, and telecommunications to transportation and critical infrastructure.  
51 The semiconductor hardware supply chain is a complex network of companies that collectively  
52 provide intellectual property, designs, and raw materials and manufacture, test, package, and  
53 distribute products. Coordination among components of a supply chain is required at different  
54 stages, including inception, deployment to end users, maintenance during use, and disposal or  
55 end-of-life. Securing semiconductor-based hardware and their supply chains helps protect  
56 sensitive information, maintain the integrity of systems, and ensure overall stability across the  
57 infrastructure and connected world.

58 Securing semiconductors involves the security of the component being built as well as the  
59 design, development, manufacturing, and distribution environments. Figure 1 illustrates the  
60 components of achieving robust semiconductor security.



61

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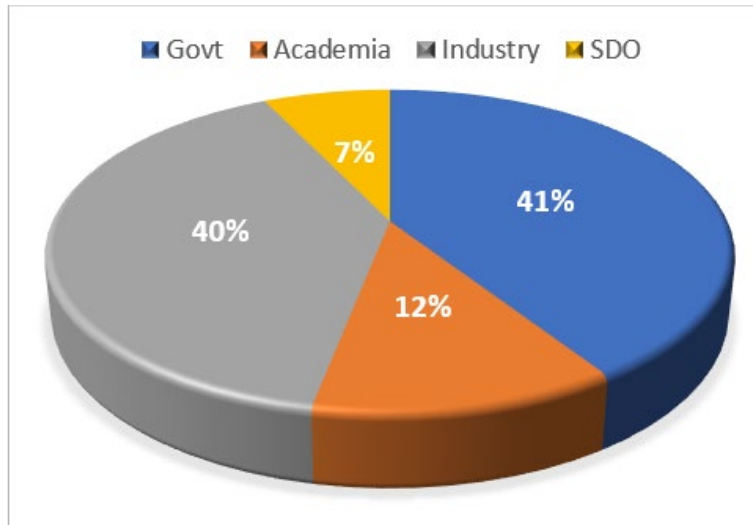
**Fig. 1. Components for securing microelectronics**

63 These activities range from physical protection mechanisms (e.g., tamper-resistant packaging)  
64 to strong encryption protocols to safeguard data. Secure boot processes ensure that only  
65 verified firmware runs, and maintaining supply chain integrity through verification and audits  
66 prevents counterfeit components. Life cycle management includes secure provisioning,  
67 updates, and end-of-life processes that are complemented by rigorous security testing and  
68 compliance with regulatory standards. Educating users on secure practices and continuously  
69 improving security measures further fortifies defenses against evolving threats and ensures that  
70 semiconductor devices operate securely throughout their life cycle.

71 The National Strategy on Microelectronics Research has emphasized the prioritization of  
72 hardware integrity and security. In response, NIST convened its inaugural workshop,  
73 “Enhancing Security of Devices and Components Across the Supply Chain”<sup>1</sup> on February 27,  
74 2024, at the National Cybersecurity Center of Excellence (NCCoE) facility. At this workshop,

<sup>1</sup> See <https://csrc.nist.gov/Events/2024/enhancing-security-of-devices-and-components>.

75 government, academia, and industry experts gathered to collaborate on research efforts, drive  
76 innovation, and establish standards, guidance, and practical implementations in a rapidly  
77 evolving landscape. The workshop was primarily an in-person event with a few remote speakers  
78 and participants. In total, there were 98 participants, with 79 participants almost evenly  
79 distributed from government and industry. The remaining 19 attendees were from academia  
80 and standards development organizations (SDOs). Figure 2 shows the distribution of  
81 participants.



82

83

**Fig. 2. Distribution of workshop participants**



## 84 2. Workshop Sessions

### 85 2.1. Hardware Development Life Cycle

86 Semiconductor and integrated circuit (IC) development is complex, non-linear, and varies from  
87 one manufacturer to another. The specialization of technologies required to design modern-day  
88 hardware has democratized the life cycle across national boundaries. This panel discussion  
89 focused on open security concerns that face the hardware development life cycle.

#### 90 2.1.1. Speaker Viewpoints

91 The panel opened with Jonathan Ring, Deputy Assistant National Cyber Director for Technology  
92 Security from the [Office of the National Cyber Director \(ONCD\)](#). Jonathan reflected that ONCD's  
93 [National Cybersecurity Strategy](#) recognizes the importance of improving the cybersecurity of  
94 the Nation's critical infrastructure, which includes restoring the production of critical goods to  
95 the United States (US) as well as improving cybersecurity in the semiconductor/IC supply chain.

96 Jonathan highlighted past achievements of the Biden-Harris Administration that overlap with  
97 cybersecurity in the hardware development life cycle, including:

- 98 • The notion of shifting the balance of security to those best suited to bear it, as  
99 represented in the Cybersecurity & Infrastructure Security Agency's (CISA) [Secure by](#)  
100 [Design](#) initiative
- 101 • The [NIST CHIPS R&D Metrology Program](#), which outlines gaps in the semiconductor  
102 ecosystem
- 103 • Ongoing work through the Subcommittee for Microelectronics Leadership
- 104 • The focus on eliminating entire classes of vulnerabilities in software in their report, [Back](#)  
105 [to the Building Blocks: A Path Toward Secure and Measurable Software](#)

106 Furthermore, Jonathan stressed the importance and continued need for public-private  
107 partnerships, like the Semiconductor Research Corporation and the Semiconductor Industry  
108 Association. He also stressed the need for continued conversations concerning advanced  
109 metrology for supply chain trust and assurance, guidelines for security analytics and  
110 automation, vulnerability management across all product life cycles, and the use of machine  
111 learning in chip design and manufacturing.

112 The second speaker for the panel was Adam Golodner, advisor to the Semiconductor Industry  
113 Association. Adam spoke about the importance of leveraging and adapting NIST resources, like  
114 the Cybersecurity Framework (CSF). Adam highlighted four key reasons why a framework for  
115 hardware security and supply chain that is similar to the CSF would be useful to the  
116 semiconductor industry:

- 117 1. Frameworks like the CSF enable thoughtful, flexible, and configurable approaches to  
118 security and allow enterprises to adopt the processes and maturity level that best move  
119 security forward for them.

- 120 2. A hardware security and supply chain framework can benefit from the recognition and  
121 adoption that the CSF has already earned.
- 122 3. The CSF and NIST have global reach and acceptance. Similarly, establishing an  
123 internationally recognized set of best practices will enhance security and innovation in a  
124 global hardware and supply chain environment.
- 125 4. NIST has the pedigree for getting security “right.”

126 Furthermore, Adam reflected that while security is core to many company brands, quantifying  
127 its return on investment is a C-suite and Board of Directors issue.

128 The last panel member was Matthew Areno, Senior Principal Engineer for Intel Corporation.  
129 Matthew admitted that there is no industry standard to describe the phases of the supply chain  
130 for ICs. However, his expertise and history with the industry have enabled him to develop his  
131 own conceptual model that is divided into seven stages: concept, development, integration,  
132 manufacturing, test, provisioning, and deployment. During his time at Intel, Matthew has  
133 worked to develop a threat model for Intel’s supply chain. Intel discovered that each of their  
134 teams approached the exercise of threat modeling in different ways, which made it difficult and  
135 time-consuming for them to exchange information. As a result, Intel has been developing and  
136 deploying a unified Threat Modeling Tool that utilizes vulnerability resources like [MITRE](#)  
137 [Common Weakness Enumeration \(CWE\)](#) to automatically make design-based suggestions on  
138 potential vulnerabilities and mitigations. The tool also forms a closed loop that incorporates  
139 knowledge learned from Intel’s own design processes.

140 Matthew also described Intel’s Transparent Supply Chain Initiative, whose goal is to provide  
141 customers with provenance and integrity data for various components during the supply chain  
142 process. He highlighted Project Amber — Intel’s Trust Authority for validating execution  
143 environments.

#### 144 **2.1.2. Key Highlights**

145 The following key points were identified during the speakers’ presentations and the Q&A  
146 portion:

- 147 • There is a definite need for continued public/private partnerships.
- 148 • There is a need for more standards around how the supply chain process is structured.
- 149 • There is a need for more standardized methods for threat modeling.
- 150 • Quantifying the return on investment for security in the supply chain is still difficult,  
151 making it challenging for those who observe deficiencies to justify addressing them to  
152 higher-level management. Possible avenues of advancement include:
- 153 ○ Developing more standardized security metrics
- 154 ○ Continuing to leverage and develop CSF-style resources to better communicate  
155 risk
- 156 ○ Framing security as a service that can be used as a revenue stream

- 157       • There is a tension between hardware security and software security due to the vastly  
158       different cost in remediating vulnerabilities at the hardware level.

## 159   **2.2. Metrology**

160   This panel focused on open issues and concerns related to security metrology and metrics (e.g.,  
161   metrics for design-for-trust techniques, metrology for the holistic assessment of power side-  
162   channel leakage across the development life cycle, metrology for analog signal security) for  
163   semiconductors and ICs throughout the hardware development life cycle.

### 164   **2.2.1. Speaker Viewpoints**

165   This session began with Lok Yan from DARPA’s Microsystems Technology Office (MTO), whose  
166   portfolio includes the Automatic Implementation of Secure Silicon (AISS) program. Lok provided  
167   a high-level overview of why the semiconductor community needs to recognize security  
168   metrics. Meaningful metrics require assets, use cases, and threats to be clearly identified within  
169   the context of a threat model. The value of assets, associated potential threats, and the  
170   consequence of an asset’s compromise must be quantifiable to support the design decision-  
171   making process.

172   Understanding and identifying a minimum acceptable security baseline within the context of a  
173   particular use case would help bring various security metrics together. Due to the continuously  
174   evolving threat space, Lok emphasized that establishing an initial set of metrics and an  
175   associated minimum security baseline is not a one-time process. Rather, they must be  
176   continuously measured, monitored, and updated as assets, threats, vulnerabilities, and use  
177   cases evolve over time. Finally, security metrics could support decisions related to the threat  
178   and vulnerability space versus the time to test or implement countermeasures. More time must  
179   be allocated to implement and test countermeasures that address the most important threats  
180   and vulnerabilities for a particular use case.

181   Jason Oberg, Cycuity CTO and co-founder, described how metrics can be used in the hardware  
182   security space based on his organization’s experience. Since different metrics are relevant to  
183   different people within an organization (e.g., metrics that work for a designer or tester may not  
184   translate to executives), there need to be different tiers of metrics based on the audience or  
185   user. For example, the CWE structure could be used to define security requirements that lead  
186   to associated security metrics. Jason noted that CWEs for hardware are relatively new, starting  
187   around 2020, compared to CWEs’ long track record for software, which started around 2006.  
188   Since CWEs point out common root cause weaknesses that lead to vulnerabilities, they foster a  
189   more proactive approach by allowing security issues to be discovered and mitigated earlier in  
190   the hardware development life cycle, thus lowering the financial impact. Having good metrics  
191   that can be used to inform design and business decisions would be helpful to the  
192   semiconductor community.

193   Finally, Mark Tehranipour from the University of Florida emphasized the importance of thinking  
194   about security and associated metrics in the early stages of the hardware development life  
195   cycle. Specifically, this involves conducting a security and risk assessment and developing a

196 security architecture during the specification and planning phases. The dynamic nature of the IC  
197 development process may impact the metrics that need to be developed, and a security metric  
198 that is suitable for the register-transfer level (RTL) may not be appropriate or work at the gate  
199 or physical level. He noted that time-to-market constraints still run on an approximately six- to  
200 nine-month cycle, but complexity has increased, leading to the need for automation in security,  
201 reliability, and testing. This increased complexity also increases the number of assets to protect  
202 and the number of potential vulnerabilities to mitigate. Regardless of what security techniques  
203 and associated security metrics are used early in the development life cycle (i.e., pre-silicon),  
204 verification is still needed during the physical layout and post-silicon stages. Finally, he  
205 identified the need for the continued development of security solutions at the material,  
206 physical, and device levels of semiconductors.

### 207 **2.2.2. Key Highlights**

208 The following key points were identified during the speakers' presentations and the Q&A  
209 portion:

- 210 • For security metrics to be meaningful, they need to be provided in the context of threat  
211 models, use cases, and vulnerable assets.
- 212 • Security metrics will need to be tailored based on where they are in the development  
213 life cycle (e.g., functional versus physical design stages) and to whom they are  
214 communicated (e.g., design engineer versus executive).
- 215 • Security must be on par with other design constraints (e.g., area, power, performance,  
216 and reliability), so having a community agreed-upon minimum security baseline might  
217 be a good first step.
- 218 • There is benefit in enhancing design tools to support security techniques and practices  
219 via automation.
- 220 • There is an opportunity to investigate the potential application of software-based  
221 security techniques and practices within the hardware domain.

### 222 **2.3. Hardware/Silicon Testing**

223 Speakers from Synopsys, PQShield, and the University of Maryland shared their expertise and  
224 vision of where the industry and technology are headed.

#### 225 **2.3.1. Speaker Viewpoints**

226 Mike Borza from Synopsys presented "Security Verification of SoC Hardware," an overview of  
227 the current status, new developments, and likely future progress in ensuring security for  
228 system-on-chip (SoC) designs. Security has begun to drive the design requirements of SoCs,  
229 which has resulted in tool vendors adding features for strong verification. Interoperability  
230 needs are also driving work on standards, such as IEEE P3164, Security Annotation for Electronic  
231 Design Interchange. Additionally, security requirements now feed into every aspect of the

232 architectural specification of a new chip and subsequent RTL design and analysis. Designs must  
233 include features such as secure boot, secure memory and interfaces, and hardware  
234 countermeasures to meet the goals of avoiding vulnerabilities. Static and dynamic verification  
235 approaches involve concentrating on formal methods early in the design process, which is then  
236 followed by simulation and testing that meet stringent coverage criteria. Mike also described  
237 tool support for all aspects of a security-focused verification platform, including the regular  
238 functional verification of security functions, checking on-chip data propagation to secure data  
239 at rest or in motion, and investigating possible tampering or intrusion.

240 It is anticipated that tool support will be improved to guarantee high levels of coverage with an  
241 improved ability to reason about the physical realizations of designs rather than only abstract  
242 descriptions. These improvements will be enhanced by developing standards to describe and  
243 communicate security information on designs and may eventually benefit from artificial  
244 intelligence/machine learning systems that incorporate knowledge of threats and potential  
245 weaknesses.

246 Niels Samwel of PQShield described his company’s work on “Automation for Side-Channel and  
247 Security Testing of Hardware IP.” Cybersecurity testing services provided by PQShield include  
248 side-channel testing and quality assurance of hardware designs. Side-channel tests can be  
249 conducted according to Federal Information Processing Standard (FIPS) 140-3 guidelines for  
250 cryptographic hardware and using Common Criteria recommendations. Using FIPS 140-3, it is  
251 possible to provide remote operation with a sufficient quantity of tests to allow for statistically  
252 valid pass-fail results. Common Criteria side-channel testing capabilities are included to  
253 estimate the number of traces required for key recovery. These test methods also make it  
254 possible to target specific vulnerabilities and attack types, including template attacks, key  
255 recovery attacks, and both correlation power analysis and differential power analysis.

256 Product quality testing services are offered for multiple phases of hardware and software  
257 product development. For digital circuit design, linting and automated field-programmable gate  
258 array (FPGA) functional testing and design implementation evaluations are provided with  
259 verification phase capabilities that include constrained random verification, coverage measures,  
260 and bounded model checking. Software assurance capabilities include static analysis and the  
261 automated testing of implementations. Verification phase processes include unit, integration,  
262 and system-level tests that also measure test coverage.

263 PQShield has integrated these testing services to develop a three-level scale for security that is  
264 tied to the levels defined in FIPS 140-3 and the Common Criteria:

- 265 • The Cloud Level of the PQShield scale targets safety against fuzzing and remote attacks  
266 and corresponds to FIPS 140-3 Level 1 or CC EAL1 and AVA\_VAN.1.
- 267 • The Edge Level of PQShield evaluates safety against “push button” physical attacks and  
268 corresponds to FIPS 140-3 software Level 2 and hardware Level 3 or CC EAL2 to 3 and  
269 AVA\_VAN.2.
- 270 • The Government Level is the highest level of the PQShield scale for safety against expert  
271 labs and corresponds to FIPS 140-3 software Level 2 and hardware Level 4 or CC EAL4+  
272 to 7 and AVA\_VAN.5.

273 The security-level scale and associated tests are intended to allow organizations to select  
274 cybersecurity evaluations according to their risk management needs.

275 Ankur Srivastava of the University of Maryland (UMD) College Park presented research on  
276 “Verification and Validation for Hardware Security Constructs,” which focuses on design  
277 obfuscation and trojan detection and mitigation measures. The need for design obfuscation  
278 arises from current practices in which a fabless IC designer outsources production of the chip to  
279 an offshore foundry. The potential risk of outsourced intellectual property piracy or  
280 counterfeiting affects both defense and industry customers, as well as the company that  
281 created the design. Logic locking obfuscation techniques have been developed to mitigate  
282 these risks, but sound measures of resistance to attack are also needed. The most researched  
283 scenario for evaluating obfuscation resistance is the case in which an attacker has a working  
284 chip that enables them to infer a design from input-output pairs or sophisticated imaging.  
285 There is less research for cases in which attackers do not have information on the design or  
286 have only a library of similar designs. Researchers have developed an extensive set of  
287 techniques to identify potential weaknesses to zero-knowledge or partial prior knowledge of  
288 designs.

289 Hardware trojans are another source of concern in hardware security. The potential exists for a  
290 malicious function to be included in a chip and triggered later by an attacker who knows the key  
291 that can be included in inputs. UMD researchers are investigating vulnerability and detectability  
292 analysis for trojan mitigation schemes. This work includes statistical analysis to determine  
293 trojan triggers and a large study evaluating the trade-offs between the likelihood of detection  
294 and the rarity/complexity of the trojan trigger using measures such as trigger length or the size  
295 of a finite state machine space that must be traversed to initiate the malicious function. This is  
296 accomplished by stress testing a spectrum of trojan types that are implemented for evaluation  
297 purposes. The area, power, and performance overheads of trojans must be evaluated because  
298 of the limits on detecting trojans by testing. Ankur emphasized the value of a strategic, layered  
299 approach to vulnerability analysis and the need for sound mathematical models (e.g., those  
300 separating trojans from bugs) to consider an attacker’s different levels of access, knowledge,  
301 and control. UMD is also developing sound metrics for hardware security constructs and  
302 security strategies for heterogeneous integration.

### 303 **2.3.2. Key Highlights**

304 The session speakers identified several needs and near-term expectations. A common theme  
305 was the need for an integrated approach to hardware security that includes advanced  
306 capabilities for all aspects of the problem. In particular, the industry should be focusing on:

- 307 • Better tool support to ensure more complete design coverage. Tool advances should  
308 also include formal approaches to reason about the physical realizations of designs  
309 beyond the current formal methods that focus on abstract representations and  
310 hardware description languages (HDLs).

- 311 • More standardized interoperability of tools and input/output. Currently, semiconductor  
312 companies tend to have their own collections of specialized tools, which makes it  
313 difficult to share information with others in the industry.
- 314 • Improved data collection and understanding of vulnerabilities. This will allow for better  
315 risk management that aligns organizational risk tolerance with appropriate levels of  
316 analysis and testing. FIPS 140-3 and the Common Criteria are useful for analyzing test  
317 and assurance approaches for deterring particular attack classes and vulnerabilities.
- 318 • Better design obfuscation techniques, as well as vulnerability and detectability analysis  
319 of malicious insertions in fabricated designs. Among the most significant risks in today's  
320 offshoring environment are the loss of intellectual property and the potential for  
321 adversaries to compromise chips with hardware trojans. Given the limitations of  
322 detecting such vulnerabilities through testing alone, hardware analyses that include  
323 power and performance overheads are essential for identifying trojans and other chip  
324 malware.

## 325 **2.4. Vulnerability Management**

326 Hardware vulnerability management shares similar challenges with well-established software  
327 vulnerability management practices and also faces its own unique challenges. The panel  
328 discussion presented three perspectives around this theme: Qualcomm's present-day  
329 experience performing vulnerability management at scale, a Battelle researcher's futurist view  
330 of defending and attacking hardware with generative AI techniques, and NIST's view on the  
331 past and present of bug classification as it applies to hardware.

### 332 **2.4.1. Speaker Viewpoints**

333 Dan O'Loughlin described how the security work of the architecture, engineering, and  
334 evaluation teams for Qualcomm's SoC portfolio drives their vulnerability management program.  
335 As he noted, Qualcomm suggested doing this at scale, thinking holistically about security and  
336 vulnerability management. Vulnerability management is an integral part of Qualcomm's overall  
337 security assurance process, for which they suggested maximizing the best outcome for planned  
338 investment. Dan recommended the categorization of the root causes for vulnerabilities  
339 throughout the life cycle (e.g., pre- and post-silicon) and how to feed back into ongoing  
340 investments and operations. The most common cause is process compliance failures, while the  
341 second most common is specification traceability gaps. Therefore, their automation has  
342 focused on addressing these causes.

343 Qualcomm suggested focusing on countermeasures for missing threat assessments, which is an  
344 important root cause. Dan's team has made additional efforts in generating and maintaining  
345 automated threat models with the help of machine-readable data formats, such as SysML. This  
346 focus on the threat model, test plan, and supporting automation allows them to scale  
347 important security checks throughout the life cycle with available staff. It is important to match  
348 threat assessment and automated testing with vulnerability detection and analysis early in the

349 life cycle. Qualcomm recommended investing heavily in this detection with fault injection, side-  
350 channel, and other techniques for pre-silicon testing. As Dan explained, this shift-left strategy is  
351 especially important for their products to detect and prevent vulnerabilities as early as possible  
352 before final certification and release to market. With all of this internal security evaluation and  
353 validation, Dan and his team have measured vulnerabilities and countermeasures over multiple  
354 generations of SoCs to confirm that the severity of findings is trending down over time.

355 However, publicly disclosing more detailed data is a different matter. Dan has been closely  
356 following regulatory changes for responsible disclosure in the software industry, but hardware  
357 vulnerability disclosure is fundamentally different. In his view, regulators and manufacturers  
358 have very different incentives, so partnership and further discussion will be required.

359 Next, Jeremy Bellay talked about Battelle’s research regarding the impact of context on proper  
360 vulnerability management. Vulnerability categorization, like CWE, provides valuable  
361 foundational context. However, higher-level, human-friendly context is still resource-intensive  
362 to produce and error-prone. One such example is the reachability analysis — how accessible a  
363 target system with a given vulnerability is to an attacker. Another example is attack chain  
364 design, where each vulnerability disclosure provides attackers more opportunities to combine  
365 multiple vulnerabilities to fully exploit a system.

366 In the past, it has been difficult to organize data for higher-level contextual information using  
367 datasets and standards from NIST, MITRE, and others. However, Jeremy’s team has recently  
368 utilized generative AI tooling to obtain this higher-level context without the additional  
369 resources needed for conventional methods. For him, the emergence of AI tools has moved the  
370 industry from the “age of context” to, as he terms it, the “age of interface.” With this  
371 perspective and tools at hand, Bellay presented his success with advanced generative AI to  
372 augment the development of attack chains with vulnerability information. This approach shows  
373 promise, yet it is not devoid of risks. Jeremy presented examples of using generative AI systems  
374 with prompts defining strict policies that tools violated, despite being given the needed  
375 context. Nonetheless, he is confident that they will improve in this age of interface and enable  
376 new capabilities for attacker and defender alike.

377 Finally, Peter Mell presented his research on the software, hardware, and trends for  
378 vulnerability management in the past, present, and future. Historically, claims of unbreakable  
379 secure software were met with skepticism, while hardware was perceived to be the immutable  
380 root of trust. This perception persisted, even though hardware is designed and programmable  
381 with software. As Peter put it, in some sense, “hardware is software.”

382 To effectively compare and contrast hardware and software, more data is needed for hardware  
383 vulnerability research. Peter compared the public infrastructure for software (e.g., CVE, NVD,  
384 CVSS, EPSS, KEV, CWE) to the current hardware vulnerability landscape. For the categorization  
385 of vulnerability types (CWE), less than half have been observed with confirmed hardware bugs,  
386 with little overlap in categories between hardware and software bugs. Additionally, Peter  
387 pointed out that he found little public evidence of hardware bugs, as opposed to thousands a  
388 year for software. He concedes that there are still some differences between hardware,  
389 software, and their vulnerabilities. Nonetheless, the paucity of data demonstrates room for  
390 improvement and a challenge to the hardware industry as it matures vulnerability management



391 practices. This research did not uncover any obstacle to utilizing public software vulnerability  
392 infrastructure for hardware vulnerability management, and he welcomes work in this area.

393 At the end of the panel, attendees asked questions about the tools and processes that aid in  
394 traceability and security. Dan described a variety of tools for security and traceability  
395 management in existing projects and greenfield projects. He repeated his praise for model-  
396 based systems engineering and tools. Jeremy agreed that those tools were helpful. There were  
397 also questions regarding the presenters' views and techniques for resourcing the experts and  
398 funding needed for outcome-focused vulnerability management. Dan explained that Qualcomm  
399 prefers actuarial methods. Peter and Jeremy emphasized the importance of methods for  
400 higher-level context and how to encourage more research in that area to support outcome-  
401 focused vulnerability management.

#### 402 **2.4.2. Key Highlights**

403 The following are some key takeaways for future work based on the presentations, feedback,  
404 and questions from the audience:

- 405 • Hardware vulnerability management could leverage public software vulnerability  
406 infrastructure, but more dialogue is needed to understand how to use it to meet  
407 hardware vendors' needs.
- 408 • Automation-friendly traceability techniques are necessary to scale the prevention and  
409 detection of vulnerabilities.
- 410 • Model-based systems engineering tools, techniques, and standards are in use, but it still  
411 needs to be determined how to measurably expand their use and incentivize industry.
- 412 • More comprehensive vulnerability data is needed to improve the taxonomies of  
413 hardware bugs that are understood and to predict those that are not.

#### 414 **2.5. Standards**

415 This session explored various aspects of hardware security standards related to semiconductor  
416 manufacturing.

##### 417 **2.5.1. Speaker Viewpoints**

418 Jeremy Muldavin represented the SAE G-32 committee and was the first presenter. He began  
419 by pointing out that while there are incentives for CHIPS fabricators to build in the US, there is  
420 currently very little market preference for an assured supply. If not corrected, the market will  
421 revert to focusing on buying cheaply, which will lead to a loss of investment. By creating  
422 standards that integrate assurance through traceability and provenance into systems  
423 engineering, the market can understand, measure, and adapt to the demand for a long-term  
424 assured supply. Jeremy stated that when the US promoted "Buy US, Build US," European  
425 customers were interested in a US supply chain, but when there appeared to be no teeth  
426 behind it, interest was lost.

427 With the amount of R&D invested in the National Semiconductor Technology Center (NSTC) and  
428 similar efforts, value must be added through assurance, or else cheaper products will take over  
429 the market again. Without knowing how to build programs that are directly tied to  
430 semiconductor manufacturing and show measurable assurance, research investments are being  
431 wasted. Agreed-upon measurable assurance requires believable standards that illuminate  
432 supply chains, identify market risks, create a basis for monetizing supply and security, and  
433 measure the impacts of assured supply. They also need to identify methods for immutable  
434 physical traceability, validate roots of trust, and identify ways to develop consumer-level  
435 traceability tools. The assurance is needed early, when the chips are inexpensive. The payoff is  
436 at the product and services end, where the applications have a far greater revenue stream.

437 Semiconductor manufacturing harvests a significant amount of data. Jeremy stated that Global  
438 Foundries accumulated about 12 terabytes of data per day. There must be an analytic  
439 environment to take advantage of that data through an “observe, orient, decide, and act”  
440 (OODA) loop to develop assurance and awareness capabilities (e.g., supply chain and digital  
441 twins capabilities) and support the stress testing of manufacturing supply disruptions in a way  
442 similar to the 2008 financial crisis bank stress testing. This would enable the transition from a  
443 trust framework of people watching people make assessments to using digital twins to model  
444 sensors and data to monitor the supply chain in a manner that creates value by establishing  
445 provenance and traceability.

446 Andrew Seward introduced the Semiconductor Manufacturing Cybersecurity Consortium  
447 (SMCC) efforts that Semiconductor Equipment and Materials International (SEMI) is  
448 implementing. SEMI is an international organization that has focused on the semiconductor  
449 industry since 1970 and provides global advocacy and technical leadership. It currently meets  
450 the cybersecurity needs of the industry, from material and equipment suppliers to end users. In  
451 November 2023, the SMCC and NIST met to identify key areas and seek volunteers for both  
452 internal leadership and action. Those attending the meeting made a good representation of all  
453 semiconductor-related industries. Starting with about 40 in-person and almost 70 online  
454 attendees, the volunteers from that group have grown to about 50+ since January 2024 and  
455 have support from several CSOs from major organizations.

456 Jennifer Lynn continued the SEMI presentation and stated that the SMCC is gaining momentum.  
457 The two days of whiteboard sessions at the November 2023 meeting established seven working  
458 groups: 1) factory cybersecurity implementation, 2) compliance readiness, 3) supply chain  
459 cybersecurity, 4) regulation and other specs, 5) threat sharing, 6) cybersecurity pre-standards  
460 engineering, and 7) outreach. Jennifer is leading working group 4, which will co-author the  
461 industry profile to map SEMI requirements to CSF 2.0. Anyone who wishes to aid in these  
462 efforts is encouraged to email [cybersecurity@semi.org](mailto:cybersecurity@semi.org) to talk to the working group leads and  
463 discuss how you might help. This work will establish the requirements for moving forward as  
464 well as how the existing structure can be protected for the rest of its lifetime.

465 The SAE G-32 is working on integrating cybersecurity assurance into a CPS systems engineering  
466 and product-focused process. The SEMI SMCC will transition the design and manufacturing  
467 floor to one that incorporates auditable cybersecurity.

468 A comment from the audience suggested that the SEMI standards for traceability at the wafer  
469 level and IPC's standards on traceability for manufacturing are a good basis for forming a liaison  
470 activity between SEMI, IPC, and SAE. NIST and other SDOs (e.g., IEEE) and entities (e.g., [IT-ISAC](#))  
471 could benefit from coordinating and participating in such efforts.

472 Another comment asked whether NIST would consider leading the effort to assess the  
473 approximately 300 related standards that already exist, potentially by employing graph  
474 analytics and other AI searching, learning, and parsing tools. It was agreed that a unified view of  
475 cybersecurity standards would help many entities better understand what is available for use  
476 and what is needed, especially with the participation of the semiconductor-related corporations  
477 that are working with the CHIPS program.

478 This opened related discussions on the use of cybersecurity standards, such as how one decides  
479 which standards to apply based on a product or organization. A comment was also made about  
480 approaching the C-suite for a semiconductor business, which appears to be more interested in  
481 a semiconductor-focused cybersecurity standard than a generic cybersecurity standard.

482 Another comment noted that creating a new standard for cybersecurity should leverage work  
483 that has been done in other areas, such as automotive or health care, and confirm applicability  
484 rather than "reinventing the wheel." In addition, requirements in standards need to be  
485 measurable. This can be difficult, as requirements are often created separately from the  
486 compliance aspect, and finding the right balance can be challenging.

487 A related comment focused on harmonizing the measurements in standards into a common or  
488 related set of metrics. In the future, it will be desirable to tailor requirements by referencing  
489 applicable parts of standards. The customer will need to assess their demand and available  
490 supply in order to verify the level of assurance required for products and services to meet their  
491 needs.

## 492 **2.5.2. Key Highlights**

493 While IT standards have continued to mature, awareness of the need for hardware standards  
494 and the importance of supply chain assurance, manufacturing policies, and resilience has only  
495 begun to grow. Cost cannot be the only consideration for semiconductor manufacturing;  
496 security and assurance value propositions and end user demand must be considered as well.

497 In the wider scope of current international supply chains, the integration of security and  
498 assurance measures is primarily relegated to larger manufacturers. Additional measures need  
499 to be uniformly integrated for both semiconductor manufacturers and their suppliers, from  
500 sophisticated equipment to raw materials. SEMI International has initiated an effort to gather  
501 all manufacturers and security and assurance experts to develop a set of standards that can be  
502 integrated into all businesses across the supply chain, with verification being a major  
503 component. This effort will reference existing IT and other non-semiconductor industry  
504 standards and work with other SDOs when such standards do not exist.

505 **2.6. Closing Remarks**

506 Serge Leef, the Secure Microelectronics Design, Implementation, and Fabrication Enablement  
507 Lead at Microsoft Azure, provided closing remarks. In “Challenges and Opportunities in  
508 Commercializing Security Research,” he addressed market barriers for hardware security  
509 products and provided an overview of the market segments:

- 510 1. Huge/large organizations for whom hardware security is a critical need and that have  
511 large teams of experts who develop appropriate solutions to address their needs across  
512 multiple high-value, large-scale products
- 513 2. Mid-size semiconductor and system companies that understand the need but lack the  
514 expertise and do not see the economic value of doing things differently
- 515 3. Defense contractors who have pockets of expertise that craft appropriate solutions to  
516 meet requirements to which they are contractually obligated
- 517 4. System integrators who are always rushed to get products to market and lack expertise  
518 to build in security and address it after deployment through patching and other means

519 Serge further stated that security automation will help 1) address the expertise gap of the mid-  
520 size and defense contractors and also 2) reduce overall cost and effort across all segments.

521 Following that, Serge provided an attack surface reference model for SoC/application-specific  
522 integrated circuits (ASICs) that examined the overall threat space for software, hardware, and  
523 software-hardware interfaces. He noted that security is difficult due to the lack of appropriate  
524 standards and a connected ecosystem, which leads to a lack of urgency and essentials. He  
525 contrasted this business problem to selling medicine: “Security is like selling vitamins — much  
526 harder than selling something like heart medication. It’s largely dependent on fear (liability)  
527 versus greed (area, speed, power). Not a good space to be in.” He offered a solution to infuse  
528 appropriate standards and regulations to tilt the equation and provided a technically  
529 implementable solution by means of his vision. He further elaborated by examining the digital  
530 broadcasting market ecosystem and drawing parallels to the semiconductor market space.  
531 Serge concluded by stating, “A supply chain trusted ecosystem alliance is essential for security.”

### 532 3. Summary and Road Ahead

533 The workshop convened a diverse array of knowledgeable individuals in the field who each  
534 brought unique expertise and insights. Through collaborative discussions and presentations,  
535 these experts offered valuable perspectives and in-depth analyses on the subject matter. Their  
536 contributions not only enriched the dialogue but also provided a comprehensive understanding  
537 of the topic from various angles.

- 538 1. Representatives from semiconductor companies discussed the proactive measures  
539 being taken to bolster security and instill trust within the industry. Deliberations  
540 centered on current insights, existing challenges, and the advancements sought by  
541 stakeholders.
- 542 2. Academic scholars discussed emerging threats and their ongoing research endeavors  
543 within academic institutions. Their discourse shed light on the evolving landscape of  
544 potential vulnerabilities and efforts to address them.
- 545 3. SDOs described their efforts dedicated to formulate robust standards that elevate  
546 security, traceability, and reliability across various sectors.
- 547 4. The government underscored its commitment to foster a conducive environment that  
548 effectively mitigates risks and to enact policies that recalibrate the risk equilibrium.

549 In consultation with relevant experts and SMEs, NIST has identified the following next steps:

- 550 • **Security for Semiconductors**
  - 551 ○ Strengthen semiconductor manufacturing through the development and  
552 adoption of a ***NIST CSF 2.0 Community Profile for Semiconductor Manufacturing***  
553 with the community (e.g., SEMI, SIA, government, academia).
  - 554 ○ In collaboration with the community, investigate and leverage existing standards  
555 and best practices to develop a ***Secure Life Cycle Framework for Semiconductors***  
556 across the supply chain, including a strategy, roadmap, appropriate  
557 recommendations that focus on semiconductor supply chain traceability and  
558 provenance, and the adaptation of current software vulnerability and patch  
559 management practices for semiconductors.
- 560 • **Metrology** — Research and formulate practical ***cybersecurity measurements and***  
561 ***metrics for semiconductors*** to continuously inform the verification and testing of  
562 countermeasures throughout the life cycle.

563 NIST is also investigating engagement mechanisms that leverage existing NIST and industry  
564 standards, guidelines, resources, and expertise to cultivate trust in semiconductors, such as  
565 public working sessions and a consortium to advance these initiatives in collaboration with  
566 industry and SDOs.

## 567 Appendix A. Workshop Agenda

### Introduction and Overview

9:00 – 9:25 ET Sanjay Rekhi – NIST  
[Kevin Stine – NIST](#)

### Hardware Development Life Cycle

9:30 – 10:30 ET Jonathan Ring – Office of the National Cyber Director  
Adam Golodner – Advisor to the Semiconductor Industry Association  
[Matt Arenó – Intel](#)  
Michael Ogata – NIST

10:30 – 10:45 ET Break

### Metrology

10:45 – 11:45 ET [Lok Yan – DARPA](#)  
[Mark Tehranipoor – University of Florida](#)  
[Jason Oberg – Cycuity, Inc.](#)  
Nelson Hastings – NIST

11:45 – 12:45 ET Lunch

### Hardware/Silicon Testing

12:45 – 13:45 ET [Mike Borza – Synopsys](#)  
[Niels Samwel – PQShield](#)  
[Ankur Srivastava – University of Maryland](#)  
Rick Kuhn – NIST

### Vulnerability Management

13:45 – 14:45 ET Dan O’Loughlin – Qualcomm  
[Jeremy Bellay – Battelle](#)  
[Peter Mell – NIST](#)  
A.J. Stein – NIST

14:45 – 15:00 ET Break

### Standards

15:00 – 16:00 [Jeremy Muldavin – Aerocyonics \(SAE-G32\)](#)  
[Andy Seward – TEL \(SEMI\)](#)  
Jennifer Lynn – IBM (SEMI)  
Kim Schaffer – NIST

### Next Steps

16:00 – 16:45 ET Serge Leef – Microsoft  
Sanjay Rekhi – NIST